STARPOWER

SEMICONDUCTOR

FRED

FD300HFE170C2S

Molding Type Module

1700V/300A 2 in one-package

General Description

STARPOWER Diode Power Module provides low forward voltage as well as low reverse recovery loss. They are designed for the applications such as SMPS.

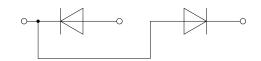
Features

- Fast soft diode
- Low forward voltage drop
- Small temperature coefficient
- Low reverse recovery losses
- High ruggedness
- Low inductance
- Isolated copper baseplate using DBC technology

Typical Applications

- SMPS
- PFC
- Electric welders
- DC choppers

Equivalent Circuit Schematic





Absolute Maximum Ratings T_c =25°C unless otherwise noted

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1700	V
I_F	Continuous Forward Current	300	A
I_{FRM}	Repetitive Peak Forward Current	600	A
P_{D}	Maximum Power Dissipation @ T _i =175°C	943	W
T_{imax}	Maximum Junction Temperature	175	°C
T_{jop}	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature Range	-40 to +125	°C
V _{ISO}	Isolation Voltage RMS,f=50Hz,t=1min	4000	V

Electrical Characteristics of Diode T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$V_{\rm F}$	Diode Forward Voltage	$I_F = 300A, T_j = 25^{\circ}C$		1.80	2.25	V
		$I_F = 300A, T_j = 125^{\circ}C$		1.90		
		$I_F = 300A, T_j = 150^{\circ}C$		1.95		
Qr	Recovered			78		μC
- Qr	Charge	$I_{F}=300A, V_{R}=900V$		70		μС
I_{RM}	Peak Reverse	$-di/dt=3600A/\mu s$		350		A
	Recovery Current	$T_i=25^{\circ}C$		330		Λ
E _{rec}	Reverse Recovery	1, 23 0		40.0		mJ
	Energy			10.0		1113
Qr	Recovered			130		μC
	Charge	$I_{\rm F}$ =300A, $V_{\rm R}$ =900V		150		μυ
I_{RM}	Peak Reverse	$-di/dt=3600A/\mu s$		380		A
*RM	Recovery Current	$T_i=125^{\circ}C$		300		71
E _{rec}	Reverse Recovery	1, 125 €		72.0		mJ
	Energy			72.0		1110
Qr	Recovered			143		μC
	Charge	$I_{F}=300A, V_{R}=900V$		1 13		μο
I_{RM}	Peak Reverse	rent -di/dt=3600A/μs T=150°C		395		A
	Recovery Current			373		<i>1</i> 1
E _{rec}	Reverse Recovery			80.5		mJ
	Energy			00.5		1110

Thermal Characteristics

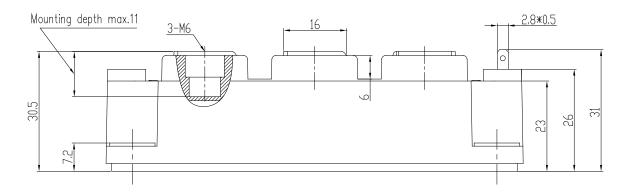
Symbol	Parameter	Min.	Тур.	Max.	Unit
L_{CE}	Stray Inductance			20	nН
R _{CC'+EE'}	Module Lead Resistance, Terminal to Chip		0.35		mΩ
R_{thJC}	Junction-to-Case (per Diode)			0.159	K/W
R _{thCH}	Case-to-Heatsink (per Module)		0.035		K/W
M	Terminal Connection Torque, Screw M6	2.5		5.0	N.m
	Mounting Torque, Screw M6	3.0		5.0	
G	Weight of Module		300		g

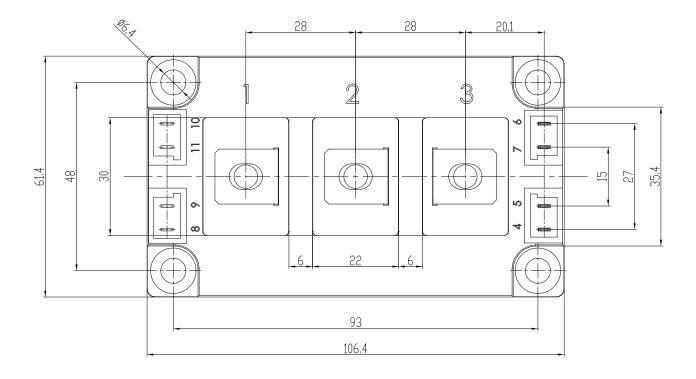
Equivalent Circuit Schematic



Package Dimensions

Dimensions in Millimeters





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